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(54) **SYSTEMS AND METHODS FOR CONFIGURING SIGNAL PATHS IN AN INTERPOSER BETWEEN INTEGRATED CIRCUITS**

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ABSTRACT

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A circuit system includes an interposer comprising conductors and switch circuits coupled to the conductors, a first integrated circuit die coupled to the interposer, and a second integrated circuit die coupled to the interposer. The first integrated circuit die comprises a primary controller circuit for configuring the switch circuits. The second integrated circuit die comprises a secondary controller circuit. The primary controller circuit configures configurable logic circuits in the second integrated circuit die by providing configuration bits to the secondary controller circuit through the interposer.

